



Material Content Data Sheet



Halogen-Free

Sales Product Name	IPSA70R900P7S	Issued	17. February 2022
MA#	MA005619995		
Package	PG-TO251-3-347	Weight*	301.19 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.203	0.40	0.40	3994	3994
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		146	
	non noble metal	iron	7439-89-6	0.146	0.05		486	
	non noble metal	copper	7440-50-8	146.214	48.55	48.61	485448	486080
wire	non noble metal	aluminium	7429-90-5	0.171	0.06	0.06	568	568
encapsulation	organic material	carbon black	1333-86-4	1.256	0.42		4169	
	plastics	epoxy resin	-	23.858	7.92		79211	
	inorganic material	silicon dioxide	60676-86-0	100.454	33.35	41.69	333521	416901
leadfinish	non noble metal	tin	7440-31-5	3.774	1.25	1.25	12531	12531
solder	non noble metal	tin	7440-31-5	0.032	0.01		106	
	noble metal	silver	7440-22-4	0.040	0.01		132	
	non noble metal	lead	7439-92-1	1.517	0.50	0.52	5038	5276
heatspreader	inorganic material	phosphorus	7723-14-0	0.007			22	
	non noble metal	iron	7439-89-6	0.022	0.01		75	
	non noble metal	copper	7440-50-8	22.455	7.46	7.47	74553	74650
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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